

(b) starting the supply of the coolant in the coolant path when the substrate or the placing table changes in state, thereby cooling the placing table together with the substrate; and

(c) unloading the substrate from the placing table after the temperature of the placing table is rendered equal to or lower than the target temperature, and heating the substrate to the target temperature in an atmosphere having a temperature substantially equal to the target temperature.

19. (New) A cooling method according to claim 18, further comprising:

starting the supply of the coolant when the temperature of the placing table changes or a predetermined time passes after the temperature of the placing table changed.

20. (New) A cooling method according to claim 18, further comprising:

starting the supply of the coolant when the substrate is placed on the placing table or when a predetermined time passes after the substrate was placed on the placing table.

21. (New) A cooling method according to claim 18, further comprising:

starting the supply of the coolant when, after the substrate is received by means of a plurality of support pins above the placing table, and the support pins are descended, or when a predetermined time passes after the support pins are descended.

REMARKS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.